

Taiwan Semiconductor

# 1A, 600V - 1000V Glass Passivated Bridge Rectifier

#### **FEATURES**

- Glass passivated junction
- Ideal for automated placement
- Reliable low cost construction utilizing molded plastic technique
- High surge current capability
- UL Recognized File # E-326854
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

### **APPLICATIONS**

- Switching mode power supply (SMPS)
- Adapters
- Lighting application

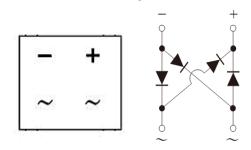
## **MECHANICAL DATA**

- Case: ABS
- Molding compound :meets UL 94V-0 flammability rating
- Packing code with suffix "G" means green compound (halogen-free)
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- Polarity: As marked
- Weight: 0.12 g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
I <sub>F(AV)</sub>	1	А		
V <sub>RRM</sub>	600 - 1000	V		
I <sub>FSM</sub>	30	А		
T <sub>J MAX</sub>	150	°C		
Package	ABS			
Configuration	Quad			







ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMETER		SYMBOL	ABS6-T	ABS8-T	ABS10-T	UNIT
Marking code on the device			ABS6	ABS8	ABS10	
Repetitive peak reverse voltage	9	V <sub>RRM</sub>	600	800	1000	V
Reverse voltage, total rms valu	е	V <sub>R(RMS)</sub>	420	560	700	V
Maximum DC blocking voltage		V <sub>DC</sub>	600	800	1000	V
Forward current On glass-epoxy		I <sub>F(AV)</sub>	0.8		- A	
Forward current On aluminum substrate			1.0			
Surge peak forward current,	$T_J = 25^{\circ}C$		30			
8.3 ms single half sine-wave superimposed on rated load	T <sub>J</sub> = 125°C		25			A
Surge peak forward current,	$T_J = 25^{\circ}C$	I <sub>FSM</sub>		60		Δ
1.0 ms single half sine-wave superimposed on rated load	T <sub>J</sub> = 125°C			50		- A
I <sup>2</sup> t value (of a surge on-state current)		l <sup>2</sup> t	3.74		A <sup>2</sup> s	
Junction temperature		TJ	-55 to +150		°C	
Storage temperature		T <sub>STG</sub>	-55 to +150		°C	



THERMAL PERFORMANCE				
PARAMETER	SYMBOL	LIMIT	UNIT	
Junction-to-lead thermal resistance	R <sub>ejl</sub>	25	°C/W	
Junction-to-ambient thermal resistance	R <sub>eja</sub>	80	°C/W	

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP.	MAX.	UNIT
Forward voltage <sup>(1)</sup>	$I_F = 0.4A, T_J = 25^{\circ}C$	V <sub>F</sub>	-	0.95	V
$\square$	T <sub>J</sub> = 25°C	I	-	10	μA
Reverse current @ rated $V_R^{(2)}$	T <sub>J</sub> = 125°C	- I <sub>R</sub>	-	150	μA

#### Notes:

1. Pulse test with PW=0.3 ms

2. Pulse test with PW=30 ms.

ORDERING INFORMATION				
PART NO.	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING
ABSxx-T	RE	G	ABS	1,000 / 7" Plastic reel
(Note 1, 2)	RG	6	ABS	5,000 / 13" Paper reel

Notes:

1. "xx" defines voltage from 600V (ABS6-T) to 1000V (ABS10-T)

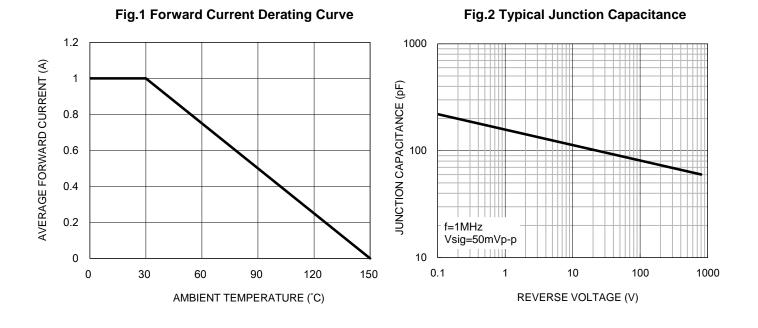
2. Whole series with green compound (halogen-free)

EXAMPLE P/N				
EXAMPLE P/N	PART NO.	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
ABS6-T REG	ABS6-T	RE	G	Green compound



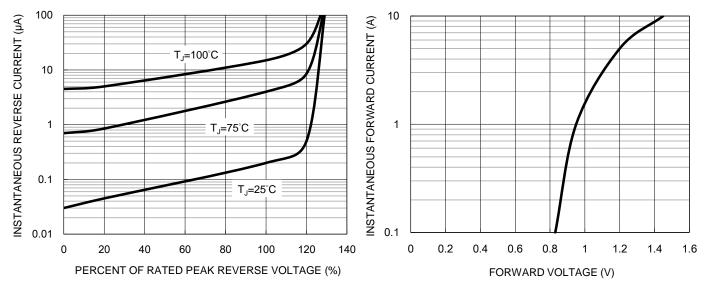
## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 



#### **Fig.3 Typical Reverse Characteristics**

**Fig.4 Typical Forward Characteristics** 

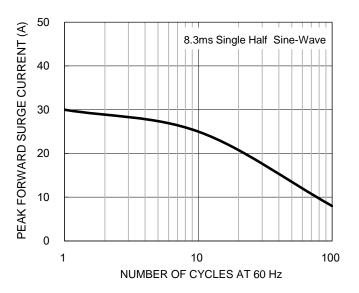




## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

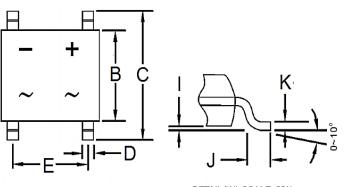
#### Fig.5 Maximum Non-repetitive Forward Surge Current





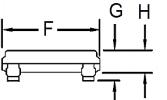
**PACKAGE OUTLINE DIMENSIONS** 

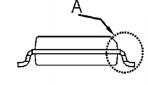
ABS



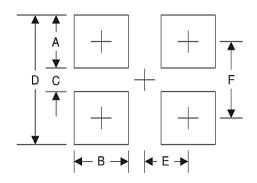
DIM.	Unit (mm)		Unit (inch)	
DIIVI.	Min.	Max.	Min.	Max.
В	4.30	4.50	0.169	0.177
С	6.25	6.65	0.246	0.262
D	0.60	0.70	0.024	0.028
Е	3.90	4.10	0.154	0.161
F	4.90	5.10	0.193	0.200
G	1.40	1.60	0.055	0.063
Н	1.35	1.45	0.053	0.057
I	0.05	0.15	0.002	0.006
J	0.30	0.70	0.012	0.028
К	0.15	0.25	0.006	0.010

DETAIL "A", SCALE=20/1





## SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
А	1.5	0.059
В	0.9	0.035
С	4.22	0.166
D	7.22	0.284
E	2.05	0.081
F	5.72	0.225

### **MARKING DIAGRAM**



P/N	= Marking Code
YW	= Date Code

F = Factory Code



Taiwan Semiconductor

## Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf, assumes no responsibility or liability for any errors or inaccuracies.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.